



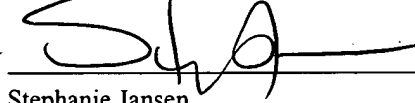
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**RESPONSE UNDER 37 C.F.R. § 1.116  
EXPEDITED PROCEDURE - EXAMINING GROUP 2800**

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PATENT #24/B

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant	: Tongbi Jiang	Attorney Docket No.	: 500182.01 (660073.774)
Serial No.	: 09/365,356	Group Art Unit	: 2813
Filed	: July 30, 1999	Examiner	: Nema O. Berezny
Title	: METHOD AND STRUCTURE FOR MANUFACTURING IMPROVED YIELD SEMICONDUCTOR PACKAGED DEVICES		

Box AF  
Commissioner of Patents  
Washington, DC 20231

**RESPONSE UNDER 37 C.F.R. § 1.116**

Sir:

Applicant acknowledges receipt of the Office Action dated September 11, 2002.

**In the Claims:**

Please amend claims 1, 11, 38 and 42 as follows:

1. (Four Times Amended) A semiconductor device package, comprising:  
a semiconductor die having a first surface on which an integrated circuit and at least one electrically conductive bond pad are fabricated, the die having first and second pairs of opposed lateral edges;  
at least one electrically conductive external terminal;